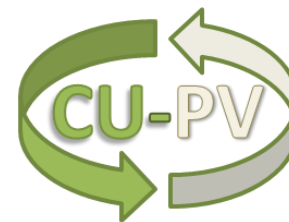


Cu-PV project 2012-2015: cradle to cradle sustainable PV modules



Cradle-to-cradle sustainable PV modules

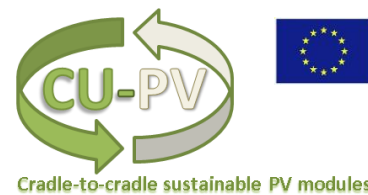


Brussels
Bart Geerligs
20 March 2017

www.sustainablepv.eu/cu-pv

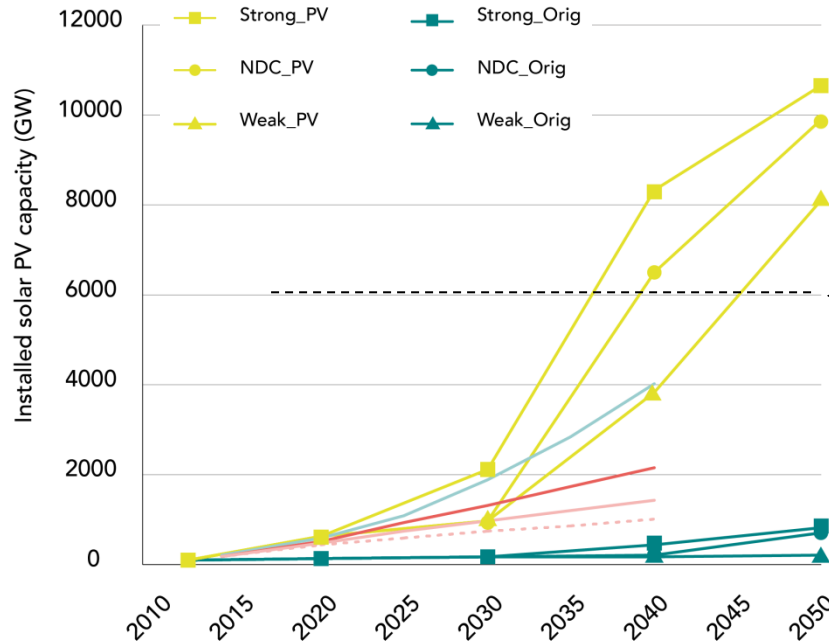
Contents

- Sustainability of PV (“photovoltaics”: solar electricity)
- The Cu-PV project: integrated technology approach on the main sustainability issues
- Partners and roles
- Conclusions and outlook



Significant growth of PV

- CO₂ footprint of PV is small: 38-82 g CO₂-eq/kWh
- Nevertheless, reduction of footprint will be beneficial



if present technology:
6-14 Gton CO₂-eq,
of which 68% for
the silicon wafer

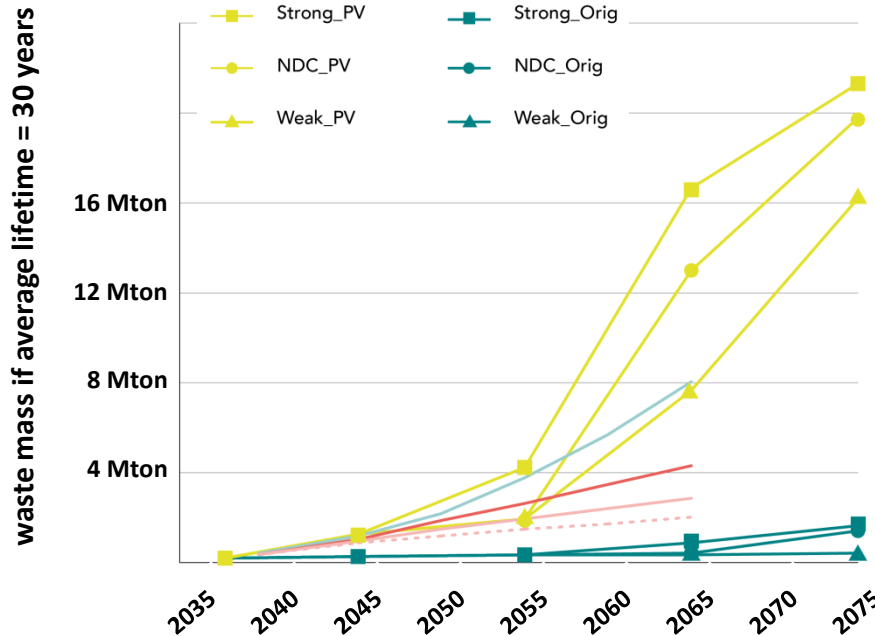
Carbon Tracker - Expect the unexpected, 2017

Sources: IEA World Energy Outlook 2016,

BNEF New Energy Outlook 2016, and CTI-Imperial analysis 2016.

Significant growth of PV

- Also waste volume has to be anticipated (with some delay)



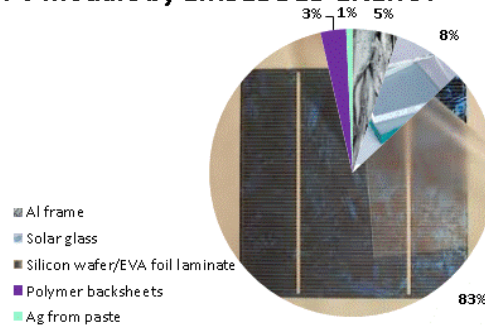
Carbon Tracker - Expect the unexpected, 2017

Sources: IEA World Energy Outlook 2016,

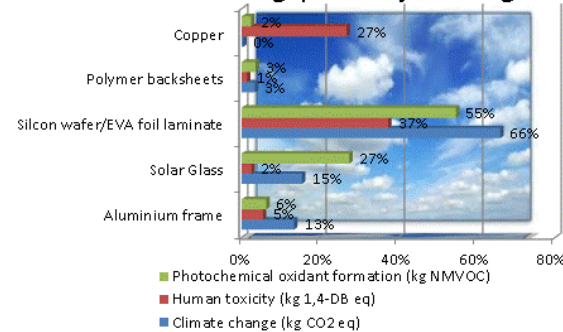
BNEF New Energy Outlook 2016, and CTI-Imperial analysis 2016.

LCA analysis of PV

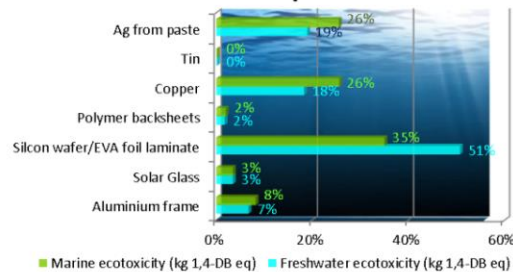
PV module by EMBEDDED ENERGY



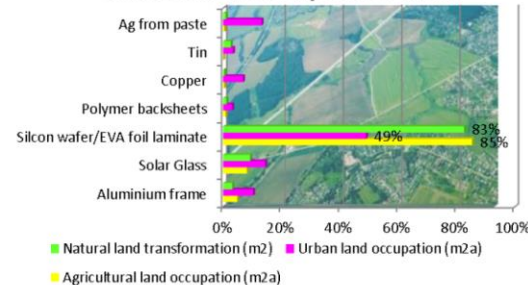
Climate change, Toxicity & Smog



Environmental Impact on Water

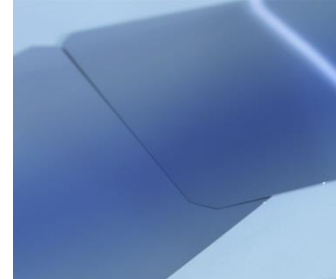
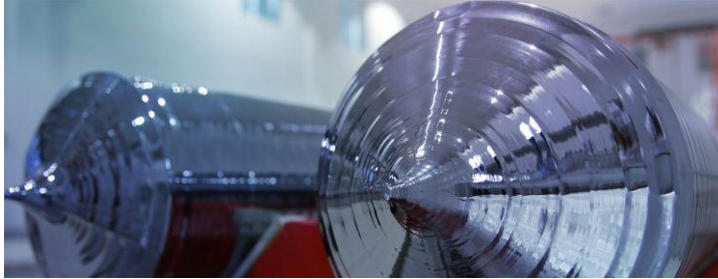


Environmental Impact on Land

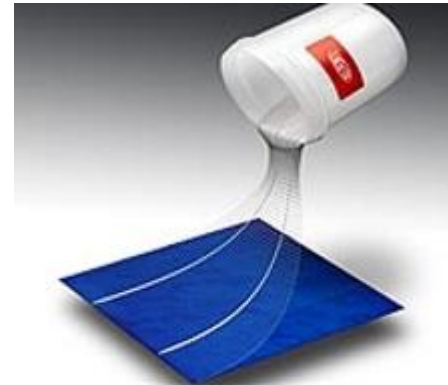


Sustainability issues tackled in the Cu-PV project

1. CO₂ footprint: mainly Si wafer: reduce thickness & recycle

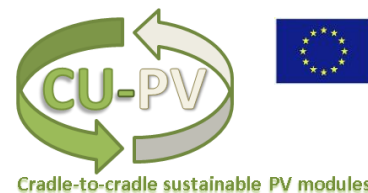


2. Ag: used for metallisation: replace
3. Recycling: increase recovered value



Project partners

- OEMs: companies making production equipment for metallisation of solar cells, and for manufacturing modules: **Xjet, Besi, Eurotron**
- End users, with own R&D:
cell and module producer: **Siliken**
SME intent on setting up recycling business: **Technical Plating**
- **PV CYCLE**: a non-profit member-based organisation managing waste (collection and recycling) for PV companies
- R&D institutes: solar cell and module technology, with track record in transfer to industry: **Imec, ECN**
LCA expertise: **ECN**



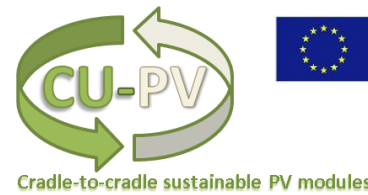
Project partners

- OEMs: companies making production equipment for metallisation of solar cells, and for manufacturing modules : **Xjet, Besi, Eurotron**

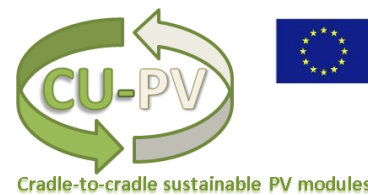
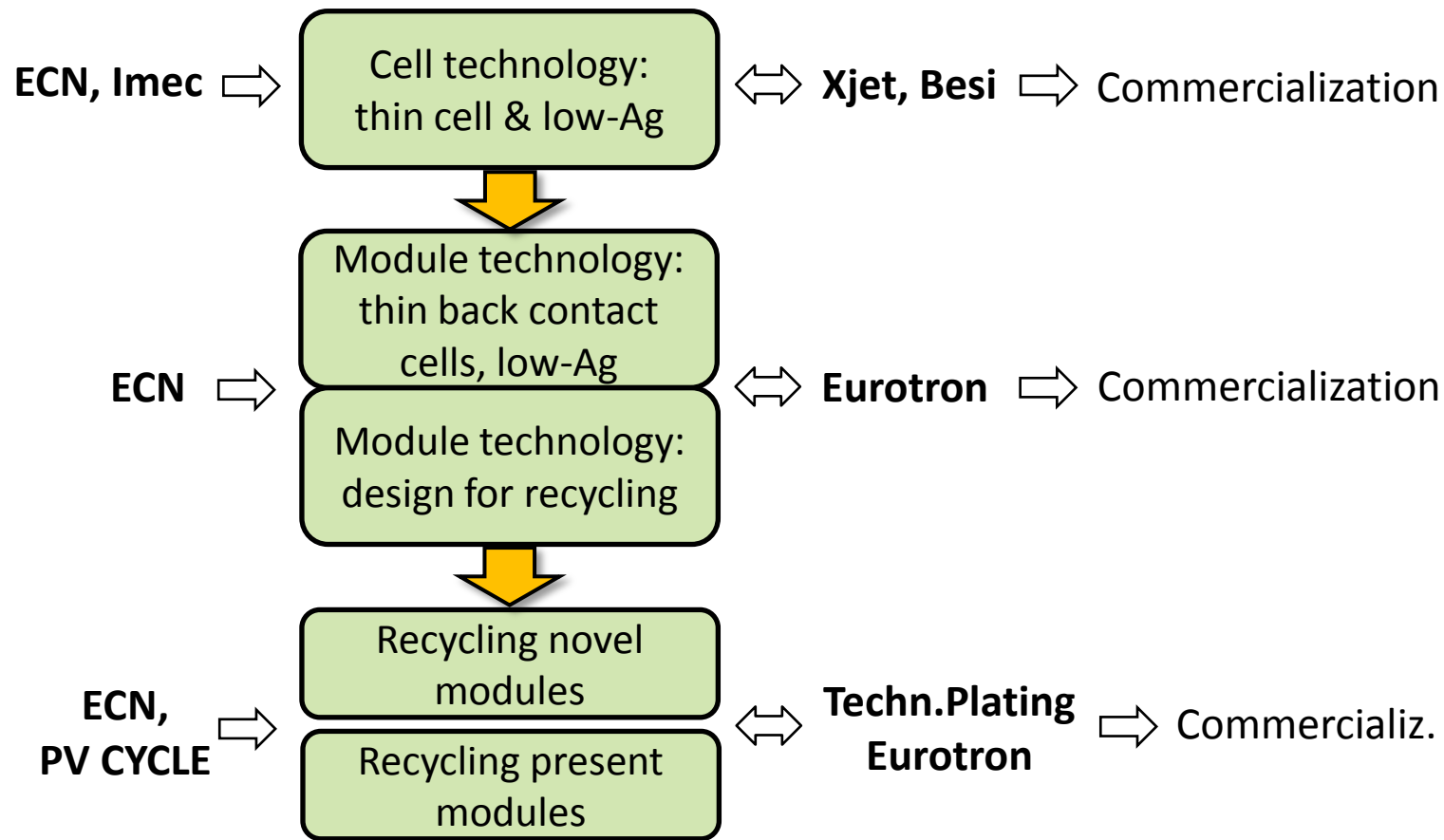
- End users, with own R&D:
~~cell and module producer: **Siliken**~~

Due to financial problems **Siliken** had to withdraw at start of project, and tasks were distributed over the other partners.

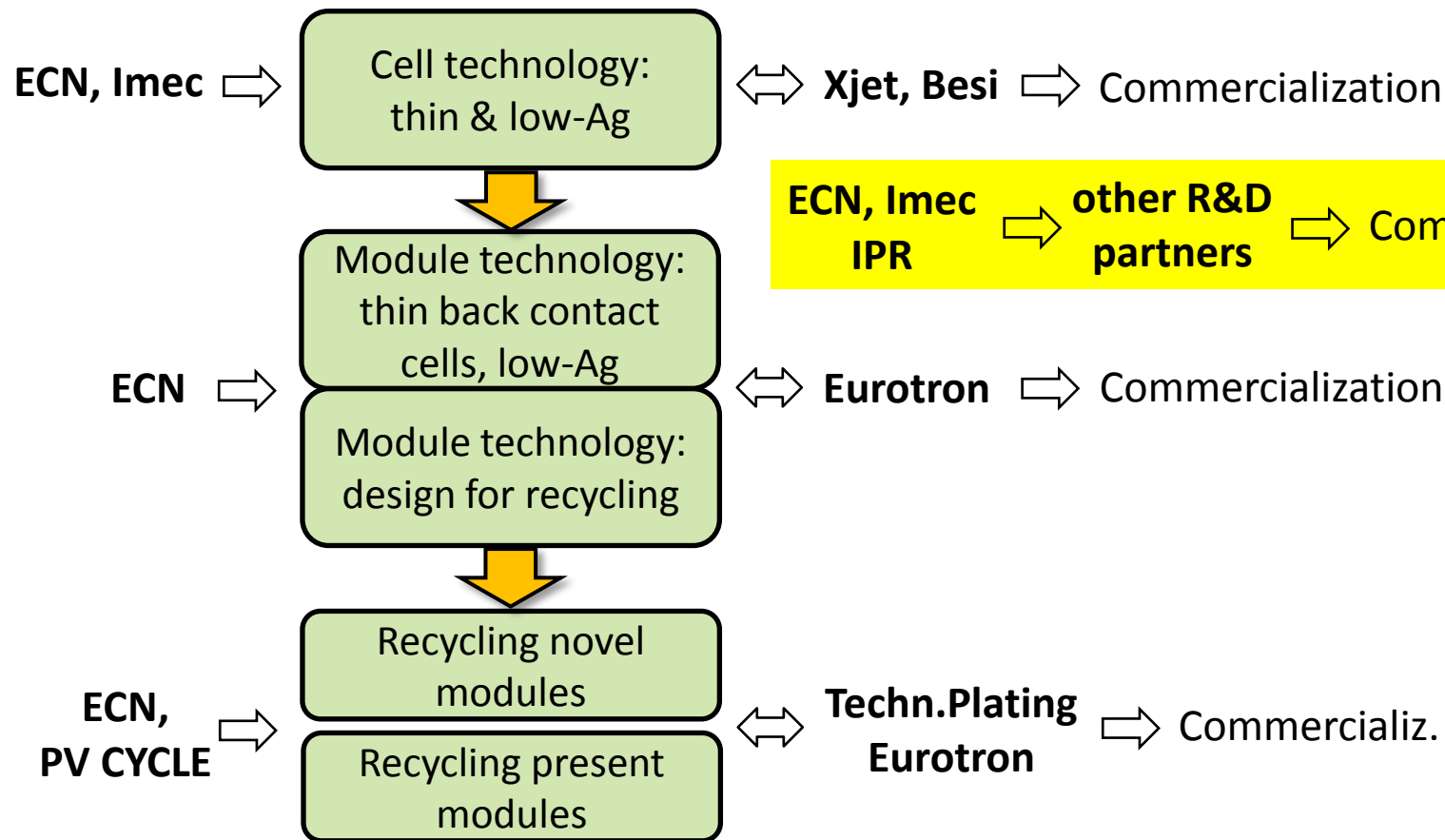
- waste (collection and recycling) for PV companies
- R&D institutes: solar cell and module technology, with track record in transfer to industry: **Imec, ECN**
LCA expertise: **ECN**



Project partners



Project partners



ECN, Imec IPR → **other R&D partners** → **Commercialization**

 **ECN**
Your energy. Our passion.

 **Besi**

 **Xjet Solar**

 **Technical PLATING**

 **EUROTRON**
POWERFUL INSTRUMENTS

 **PV CYCLE**

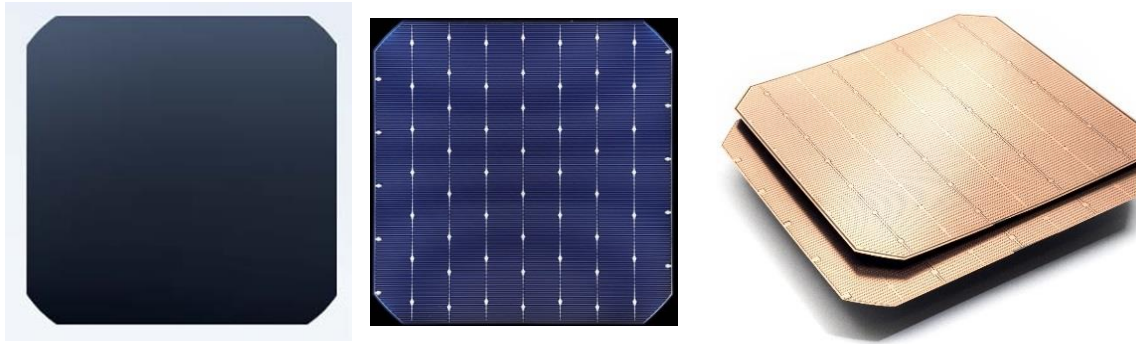
Project approach

- Multiple technology development lines
 1. very close to industry – for rapid introduction & rapid benefit to industry partners
 - print seed&plate metallization; recycling of present PV modules
 2. more advanced technology – with more environmental benefit
 - PVD seed&plate metallization; design for recycling
- Interaction between the solutions for the different problems
 - New module technology to reduce silicon consumption *and at the same time* enhance recyclability
 - New cell technology to reduce silicon consumption *and at the same time* allow solutions to reduce silver consumption
- PV CYCLE as watch-dog for feasibility of recycling; and feedback from network (e.g. survey at start of project, workshop)

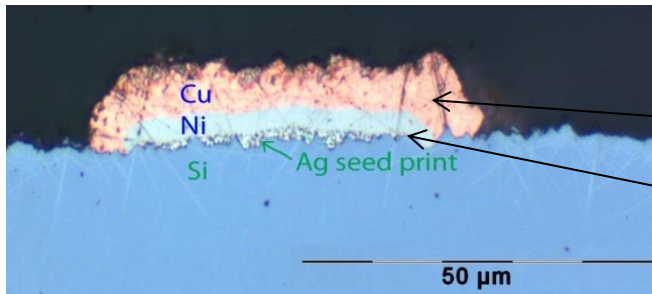


Cu-PV solar cells

- contacted on rear only - less stress in module -allowing thinner wafers



- instead of Ag contacts, using a Cu-plated layer stack

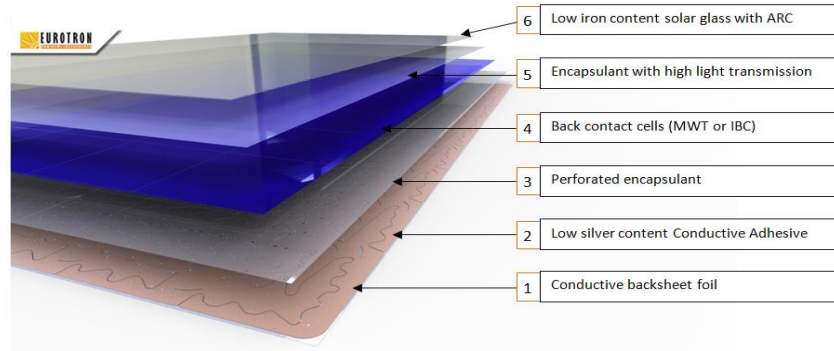


Besi-Meco NiCu plate

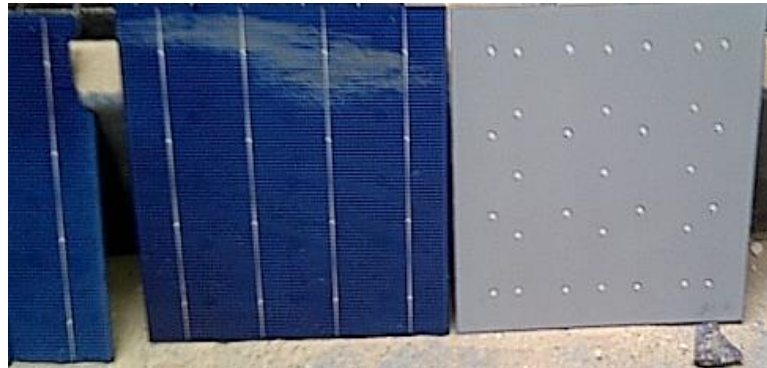
Xjet seed print
90% Ag reduction

Cu-PV modules

- back-contact module technology - allowing extremely thin cells (120 μm in project, recently 80 μm)

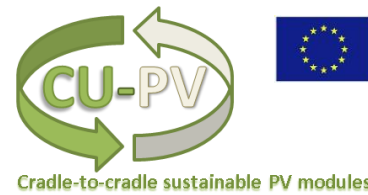


- thermoplastic encapsulant, modified frame and backsheet - allowing full wafer/cell recovery



Some results

- Cell technology – cell thickness from 180 μm to 120 μm ; Ag consumption reduced by 70%/90%/>95%; efficiency to 22.5%
- Module technology – Pb-free interconnection; back-contact technology for 6" interdigitated-back-contact cells; thermoplastic encapsulation; F-free backsheet; new framing
- Recycling – for present conventional modules: enhanced separation – backsheet, silver, clean glass, (silicon) recovered; for thermoplast based modules: recovery of intact glass sheets and large fraction of intact wafers



Plating

- Plate-on-PVD-seed metallization process for IBC developed
 - Ag reduction >95% (Ag capping layer still required)
 - efficiency 22.5%
 - 120 μm thin cells; handling of 100 μm thin wafers
 - Dissemination: conferences, exhibitions, customer contacts
- Plate-on-seed line sold by Mecob-Besi
Confident about market growth



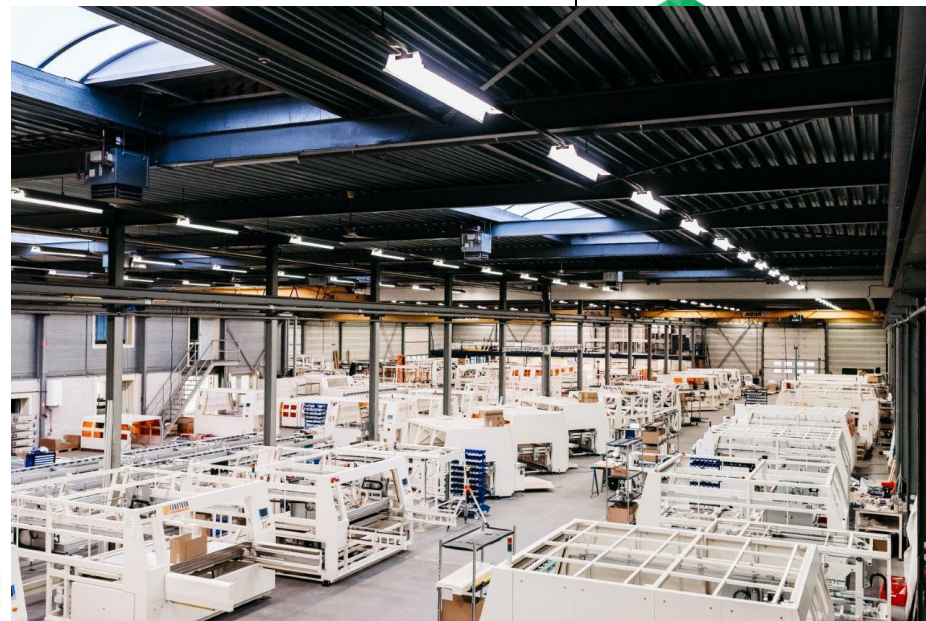
Seed printing for plating

- Plate-on-printed-seed metallization process developed for all solar cell architectures, including standard industrial
- Ag reduction 90% for inkjet printing, 70% for screen printing
- 120 μm thin cells
- Close to industrial process, proven, yet limited industry interest
- Xjet decided to withdraw from PV business
- Xjet willing to license technology



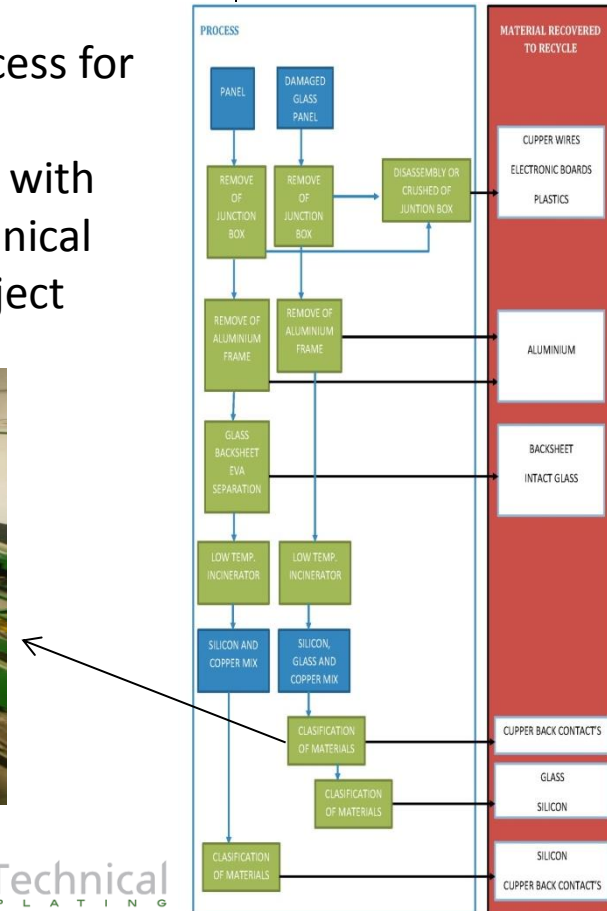
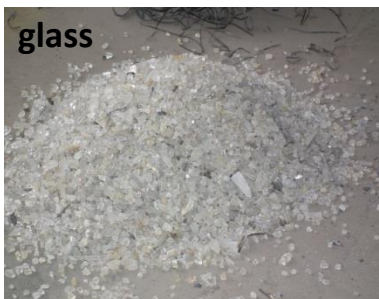
Back contact module technology

- Technology for IBC cells, 120 μm thickness (recently 80 μm), thermoplastic encapsulant, production conductive backsheet.
- Dissemination: conferences, exhibitions, customer contacts
- Several production lines sold; press release in April 2017
- Technology ready for drastic reduction of Si wafer thickness – however currently manufacturers still use normal wafer thickness



Recycling

- Semi-automated disassembly / thermal / sorting process for recycling of current PV modules
- Positive business case evaluation by Technical Plating with support from PV CYCLE and ECN – unfortunately Technical Plating encountered financial problems at end of project



Conclusions and outlook

- Mix of complementary partners along the value chain
- 3x price drop of PV modules during 2010-2012 caused problems for partners, and in general reduces adoption of innovations
- Inkjet seed printing technology was possibly too disruptive
- Back contact module technologies either moved to production or are in further test&development for production
 - wafer thickness should follow suit, if only for cost reasons
 - environmental footprint labeling would help
- Back contact cell technologies moved to industrial tests
- Adoption of project recycling technologies and design for recycling face challenges of relatively low value of component materials, and reliable supply of end-of-life modules
 - environmental footprint labeling might help

